IPC ASSOCIATION ELECTRONIC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved international and Pan-American copyright conventions.			nder both				ces within the manu ower level materials					
752-21.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Type Distribute			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
upplier	r Information													
Company name* Company unique ID					τ	Unique ID Authority			Respo	Response Date*				
nsemi										2024-05-01				
Contact Name Titl				Title - Contact			Phone - Contact*			Email	Email - Contact*			
roduct-F	Env-Stewards	Product Enviro Compliance			1	NA			Prod	Product-Env-Stewards@onsemi.com				
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	Requester Item Number Mfr Iter		Number Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type		
		NFAL50)65L4BT	650V/50A Large I	DIP		2024-05-01		СРА		47932.68	mg	Each	
	cturing Process Informa		Farminal Daga	Allow	-STD-020 MS	I. Dotino	Pools Progo	as Dody Tompo	oture Moy Time at	Dools Tompo	notine Nimbe	or of Doflay, Cv	olog	
	8		Γerminal Base Alloy J-STD-020 MSI CU Alloy NA		L Kating	Peak Process Body Temperature Max Time at Po		1	ak Temperature Number of Reflow Cycles seconds 3					
omments	. ,		CO Alloy	1	1/1		υ	IC_	30	Isec	onus J			
minents														
	information regarding material		1 6 4											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
irective 2015/863/EU amending RoHS irective 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Isability and the Company's remedies for issues that arise regarding information the Supplier pro											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-6_									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
DBC	7836.77	mg	Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1449.8025	mg
			Supplier	Copper (Cu)	7440-50-8		6386.9673	mg
Die	126.17	mg	Supplier	Silicon (Si)	7440-21-3		126.17	mg
Die Attach	101.19	mg	Supplier	Silver (Ag)	7440-22-4		2.5298	mg
			Supplier	Tin (Sn)	7440-31-5		93.6008	mg
			Supplier	Copper (Cu)	7440-50-8		5.0595	mg
Die Attach Epoxy	9.58	mg	Supplier	Silver (Ag)	7440-22-4		8.8136	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.7664	mg
Die Attach Solder	20.14	mg	Supplier	Silver (Ag)	7440-22-4		0.5035	mg
			A	Lead (Pb)	7439-92-1	7a	18.6295	mg
			Supplier	Tin (Sn)	7440-31-5		1.007	mg
Lead Frame	3926.73	mg	Supplier	Zinc (Zn)	7440-66-6		4.7121	mg
			Supplier	Iron (Fe)	7439-89-6		92.2782	mg
			Supplier	Copper (Cu)	7440-50-8		3828.5618	mg
			Supplier	Phosphorus (P)	7723-14-0		1.178	mg
Mold Compound-Black	35664.24	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		1426.5695	mg
			Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		1426.5695	mg
			Supplier	Carbon Black (C)	1333-86-4		178.3212	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		30849.5664	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		356.6424	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1426.5695	mg
NTC	1.64E-4	mg	Supplier	Silver (Ag)	7440-22-4		0	mg
			Supplier	Tin (Sn)	7440-31-5		0	mg
			Supplier	Nickel Oxide (NiO)	1313-99-1		0.0001	mg
			Supplier	Palladium (Pd)	7440-05-3		0	mg
			В	Nickel (Ni)	7440-02-0		0	mg
			Supplier	Cobalt Oxide (Co3O4)	1308-06-1		0	mg
			Supplier	Manganese Tetraoxide (Mn3O4)	1317-35-7		0.0001	mg
Plating	26.97	mg	Supplier	Tin (Sn)	7440-31-5		26.97	mg
Wire Bond - Al	220.14	mg	Supplier	Aluminum (Al)	7429-90-5		220.14	mg

Wire Bond - Au	0.75	mg	Supplier	Gold (Au)	7440-57-5	0.75	mg